



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Shibaek Nam; Oseob Jeon; and Chulho Heo
Assignee: Fairchild Semiconductor Corporation
Title: Semiconductor Device Having Multi-Chip Package Structure
Application No.: 10/038,714 Filing Date: January 2, 2002
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Docket No.: M-11590 US Confirmation No.: 8922

San Francisco, California
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COMMISSIONER FOR PATENTS
Washington, D. C. 20231

NOTICE OF CHANGE OF ADDRESS

Dear Sir:

Please direct all correspondence in the above-identified application and with respect to any patent that issues on this application to the undersigned at this address:

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I hereby certify that this correspondence is being deposited with the United States Postal Service on the date shown below with sufficient postage as first class mail in an envelope addressed to: Commissioner for Patents, Washington, D.C. 20231.

Respectfully submitted,

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